

Preliminary Product Information

PRODUCT FEATURES

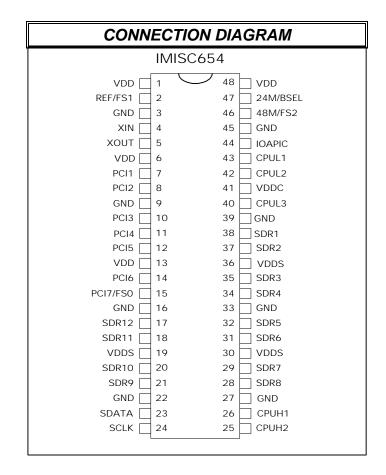
- Individual I²C clock stop controls for low power mobile applications and EMI reduction
- Designed to meet Inteltm specifications
- Integrated crystal loading capacitors
- Supports Intel Pentium, Pentium Pro, Pentium II, Cyrix and AMD CPU's
- 7 PCI BUS clocks (synchronous or asynchronous)
- <250 pS skew on all CPU/SDRAM clocks
- <500 pS between CPU and PCI clocks</p>
- 2 Ref. Clocks @ 14.31818 MHz, one at VDDC (IOAPIC)
- Separate V_{DDC} for CPUL (1:3) clock buffers and IOAPIC
- Programmable registers for jumperless frequency selection
- 48 Pin SSOP Package

BLOCK DIAGRAM Xin OSC REF/FS1 Xout FS2 48M/FS2 PLL1 BSEL 24M/BSEL 32M IOAPIC VDDC - CPUL (1:3) FS(0:2) CPUH(1:2) PLL2 LATCH SDR (1:12) VDDS SDATA I CONTROL E3 **LOGIC** SCLKT PCI (1:6) PCI7/FS0 BSFI

PRODUCT DESCRIPTION

The device is a high fanout EMI reducing system clock generator that provides the large quantity of clocks needed to support the motherboard. Bi-directional I/O pins are provided to maximize the functionality of the device and provide the input control features required for user flexibility.

	FREQUENCY TABLE (MHz)							
	(Functionality with 14.31818 MHz input)							
Freq	uency S	Select	CPUs	PC	l (1:6)			
FS2	FS1	FS0	MHz	BSEL = 1	BSEL = 0			
0	0	0	60.0	30.0	32.0.			
0	0	1	66.8	33.4	32.0			
0	`1	0	50	25.0	32.0			
0	1	1	55	27.5	32.0			
1	0	0	75	37.5	32.0			
1	0	1	68.7	34.4	32.0			
1	1	0	83.3	41.7	32.0			
1	1	1	Tri-state	Tri-state	Tri-state			





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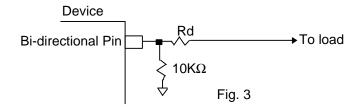
				PIN DE	SCRIPTION
PIN No.	Pin Name	POWE R	I/O	TYPE	Description
4	Xin	VDD	I	OSC1	On-chip reference oscillator input pin. Requires either an external parallel resonant crystal (nominally 14.318 MHz) or externally generated reference signal. Has internal 18 pF crystal loading capacitor.
5	Xout	VDD	0	OSC1	On-chip reference oscillator output pin. Drives an external parallel resonant crystal. When an externally generated reference signal is used, this pin is left unconnected. Has internal 18 pF crystal loading capacitor.
40, 42, 43	CPUL[1:3]	VDDC	0	BUF1	Clock output. CPU frequency table specified. Power is applied by VddC
38, 37, 35, 34, 32, 31, 29, 28, 21, 20, 18, 17	SDR [1:12]	VDDS	0	BUF2	Clock output. Low skew copy of the CPU clock used to drive SDRAM clock pins.
25, 26	CPUH(1:2)	VDD	0	BUF1	Clock output. Low skew copy of the CPU clock used to drive SDRAM clock pins. Powered is applied by Vdd
7, 8, 10, 11, 12, 14	PCI [1:6]	VDD	0	BUF1	Clock output. PCI Bus frequency table specified. Power is applied by VDD Pins.
46	48M/FS2	VDD	I/O	BUF 2 PU	Bi-directional pin. During powerup sets the FS2 bit. Afterwards, it is a 48.0 MHz output clock. Has internal pullup.
2	REF/FS1	VDD	I/O	BUF4 PU	Bi-directional pin. During powerup sets the FS1 bit. Afterwards, it is a 14.31818 MHz reference output clock. has internal pullup
47	24M/BSEL	VDD	I/O	BUF 2 PU	Bi-directional pin. During powerup sets the bus mode (BSEL) bit. Afterwards, it is a 24.0 MHz reference output clock.
15	PCI7/FS0	VDD	I/O	BUF3 PU	Bi-directional pin during power up. Its logic level is latched and defines the selection of the frequency table. as FS0. After power up it acts as a PCI clock output as defined by the PCI [1:6] pins.
23	SDATA		I	PAD PU	I ² C data input pin Has internal pullup.
24	SCLK		I	PAD PU	I ² C clock input pin. Has internal pullup.
1,6, 13, 48	VDD		PWR		3.3 volt core, PCI clock and fixed clock power.
41	VDDC		PWR		3.3 or 2.5 volt CPU clock power
19, 30, 36	VDDS		PWR		3.3 volt power for SDRAM and CPUH buffers
3, 9,16,22, 27,33,39, 45	GND		PWR		Device ground
44	IOAPIC	VDDC	0	BUF4	This is a 14.31818 MHz clock. Its output buffers is supplied by the VDDC and may be as 2.5 volts.



Preliminary Product Information

Selection on Bi-directional Pins

Bi-directional pins and are used for selecting different functions in this device (see Pin description, Page 2). During power-up of the device, these pins are in input mode and therefore, they are considered input select pins. Internal to the IC, these pins have a large value pull-up each ($100K\Omega$), therefore, a selection "1" is the default. If a selection "0" is desired, then a direct connection to ground through a $10K\Omega$ resistor should be implemented as shown in Fig.3. Please note the selection resistor ($10K\Omega$) is placed before the Damping resistor (Rd) and close to the devices pin.



2-WIRE I'C CONTROL INTERFACE

The 2-wire control interface implements a write only slave interface. The device cannot be read back. Sub-addressing is not supported, thus all <u>preceding bytes must be sent</u> in order to change one of the control bytes. The 2-wire control interface allows each clock output to be individually enabled or disabled.

During normal data transfer, the SDATA signal only changes when the SDCLK signal is low, and is stable when SDCLK is high. There are two exceptions to this. A high to low transition on SDATA while SDCLK is high is used to indicate the start of a data transfer cycle. A low to high transition on SDATA while SDCLK is high indicates the end of a data transfer cycle. Data is always sent as complete 8-bit bytes, after which an acknowledge is generated. The first byte of a transfer cycle is a 7-bit address with a Read/Write bit as the LSB. Data is transferred MSB first.

The device will respond to writes to 10 bytes (max) of data to address <u>D2</u> by generating the acknowledge (low) signal on the SDATA wire following reception of each byte. The device will not respond to any other control interface conditions. Previously set control registers are retained.



Preliminary Product Information

SERIAL CONTROL REGISTERS

NOTE: The Pin# column lists the affected pin number where applicable. The @Pup column gives the state at true power up. Bytes are set to the values shown only on true power up.

Following the acknowledge of the Address Byte (D2), two additional bytes must be sent:

- 1) "Command Code " byte, and
- 2) "Byte Count" byte.

Although the data (bits) in these two bytes are considered "don't care", they must be sent and will be acknowledged.

After the Command Code and the Count bytes have been acknowledged, the below described sequence (Byte 0, Byte 1, Byte2,) will be valid and acknowledged.

Byte 0: CPU Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description					
7	1	*	BSEL (frequency Table Selection via I ² C)					
6	1	*	FS2 (frequency Table Selection via I ² C)					
5	1	*	FS1 (frequency Table Selection via I ² C)					
4	1	*	FS0 (frequency Table Selection via I ² C)					
3	0	*	enable frequency selection by hardware (set to 0) or					
			software I ² C (set to 1)					
2	Χ	n/a	Reserved for future Spread Spectrum function					
1	0	*	Bit 1 Bit 0					
0	0	*	1 1 Tri-State					
			1 0 Reserved for IMI testing function					
			0 1 Test Mode					
			0 0 Normal					

Function Table

Function	Outputs								
Description	CPU	PCI	SDRAM	REF	IOAPIC				
Tri-State	Hi-Z	Hi-Z	Hi-Z	Hi-Z	Hi-Z				
Test (BSEL=1)	Tclk/2	Tclk/4	Tclk/2	Tclk	Tclk				
Test (BSEL=0)	Tclk/2	Tclk/3	Tclk/2	Tclk	Tclk				
Normal	see table	see table	CPU	14.318	14.318				

Notes:

^{1.} Tclk is a test clock over driven on the Xin input during test mode.



Preliminary Product Information

SERIAL CONTROL REGISTERS (Cont.)

Byte 1: **CPU**, **SIO**, **USB Clock Register (**1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description			
7	1	46	48 MHz enable/Stopped			
6	1	47	24 MHz enable/Stopped			
5	Х	-	Reserved			
4	1	25	CPUH2 enable/Stopped			
3	1	26	CPUH1 enable/Stopped			
2	1	40	CPUL3 enable/Stopped			
1	1	42	CPUL2 enable/Stopped			
0	1	43	CPUL1 enable/Stopped			

Byte 2: PCI Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description			
7	Х	ı	Reserved			
6	1	15	PCI7 / FS0 enable/Stopped			
5	1	14	PCI6 enable/Stopped			
4	1	12	PCI5 enable/Stopped			
3	1	11	PCI4 enable/Stopped			
2	1	10	PCI3 enable/Stopped			
1	1	8	PCI2 enable/Stopped			
0	1	7	PCI1 enable/Stopped			

Byte 3: SDRAM Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description			
7	1	28	SDRAM8 enable/Stopped			
6	1	29	SDRAM7 enable/Stopped			
5	1	31	SDRAM6 enable/Stopped			
4	1	32	SDRAM5 enable/Stopped			
3	1	34	SDRAM4 enable/Stopped			
2	1	35	SDRAM3 enable/Stopped			
1	1	37	SDRAM2 enable/Stopped			
0	1	38	SDRAM1 enable/Stopped			



Preliminary Product Information

SERIAL CONTROL REGISTERS (Cont.)

Byte 4: Additional SDRAM Clock Register (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description			
7	Х	-	Reserved			
6	Х	-	Reserved			
5	Х	-	Reserved			
4	Х	-	Reserved			
3	1	17	SDRAM12 enable/Stopped			
2	1	18	SDRAM11 enable/Stopped			
1	1	20	SDRAM10 enable/Stopped			
0	1	21	SDRAM9 enable/Stopped			

Byte 5: Peripheral Control (1 = enable, 0 = Stopped)

Bit	@Pup	Pin#	Description			
7	Х	-	Reserved			
6	Х	1	Reserved			
5	Х	-	Reserved			
4	1	44	IOAPIC enable/Stopped			
3	Х	1	Reserved			
2	Х	-	Reserved			
1	Х	-	Reserved			
0	1	2	REF1/FS1 enable/Stopped			

Byte 6: Reserved Register

Bit	@Pup	Pin#	Description
7	Х	•	Reserved
6	Х	•	Reserved
5	Х	-	Reserved
4	Х	-	Reserved
3	Х	-	Reserved
2	Х	-	Reserved
1	Х	-	Reserved
0	Х	-	Reserved



Preliminary Product Information

MAXIMUM RATINGS

7 V Maximum Power Supply: Vin Relative to VSS: -0.3V to VDD+0.3 Storage Temperature: -65°C to + 150°C -55°C to +125°C Operating Temperature: Maximum Power Dissipation: ESD: 12Kv(inputs), 2Kv (outputs)

Note. All Vdd and Vss pins must be connected to their required potentials to avoid device damage

This device contains circuitry to protect the inputs against damage due to high static voltages or electric field; however, precautions should be taken to avoid application of any voltage higher than the maximum rated voltages to this circuit. For proper operation, Vin and Vout should be constrained to the range:

VSS<(Vin or Vout)<VDD

Unused inputs must always be tied to an appropriate logic voltage level (either VSS or VDD).

ELECTRICAL CHARACTERISTICS							
Characteristic	Symbol	Min	Тур	Max	Units	Conditions	
Input Low Voltage	VIL	-	-	0.8	Vdc	All logic inputs	
Input High Voltage	VIH	2.0	-	-	Vdc	All logic inputs	
Input Low Current	IIL			-66	μA	All logic inputs	
Input High Current	IIH			5	μA	All logic inputs	
Tri-State leakage Current	loz	-	-	10	μA	All logic outputs	
Static Supply Current	Isdd			22	mA	CPU = 66.6 Mhz, no clocks loaded	
Dynamic Supply Current	ldd	-	-	84	mA	CPU = 66.6 Mhz, all clocks at specified max capacitance	
Powered down Supply Current	lpd		-	128	μA	PD pin at Vss level	
Input Capacitance Logic Gates	Cli	3	-	5	pF	All logic input pins	
Input Capacitance Xin andXout pins	Cioi, Cioo	5	-	8	pF	Reference Oscillator pins. Effective load to crystal is half this value.	
VDD =	VDD =3.3 +	·/- 5%, \	VDDC =	= 2.5V +/-	5%, TA =	0°C to +70°C	



Preliminary Product Information

TIMING CHARACTERISTICS								
Parameters	Symbol	Min	Тур	Max	Units	Conditions		
CPU to CPU Skew	Tskw1	-	-	250	pS	20 pF Load, Measured @ 1.25V		
SDRAM to SDRAM Skew	Tskw2	-	-	250	pS	30 pF Load, Measured @ 1.5V		
CPU to SDRAM Skew	Tskw3	-	-	500	pS	CPU: 20 pF Load, Measured @ 1.25V		
						SDRAM: 30 pF Load, Measured @ 1.5V		
PCI to PCI Skew	Tskw4	-	-	500	pS	30 pF Load, Measured @ 1.5V		
CPU to PCI Offset	Toff	1	-	4	nS	CPU: 20 pF Load, Measured @ 1.25V		
						PCI: 30 pF Load, Measured @ 1.5V		
Output Duty Cycle	Tdty	45	50	55	%	CPU, IOAPIC: 20 pF Load, Meas. @ 1.25V		
Cycle to Cycle Jitter	Tccj	250	-	250	pS	PCI, SDRAM, REF, 48MHz, 24MHz : 30 pF		
Long Term Jitter	Tj	-	-	500	pS	Load, Measured @ 1.5V		
VD	$VDD = VDD = 3.3V + /-5\%$, $VDDC = 2.5V + /-5\%$, $TA = 0^{\circ}C$ to $+70^{\circ}C$							

BUF1 (CPU clocks)								
Characteristic	haracteristic Symbol Min Typ Max Units Conditions							
pull-up Current	IOH	-27	-	-27	mA	$VOH_{min} = 1.0V$, $VOH_{max} = 2.6$		
Pull-Down Current	IOL	27	-	27	mA	$VOL_{min} = 1.2v$, $VOL_{max} = 0.3V$		
Rise/Fall times	Tr, Tf	0.4	-	1.6	nS	20 pF Load, Measured @ 0.4V to 2.0V		
Clock High Time Thi 5 nS 20 pF Load, Measured @ 2V								
Clock Low Time Tlo 5 nS 20 pF Load, Measured @ 0.4V								
$VDD = VDD3 = 3.3V + -5\%$, $VDDC = 2.5V + -5\%$, $TA = 0^{\circ}C$ to $+70^{\circ}C$								

BUF2 (REF and SDRAM clocks)								
Characteristic Symbol Min Typ Max Units Conditions								
Pull-Up Current	IOH	-46	-	-46	mA	$VOH_{min} = 1.0V, VOH_{max} = 2.6$		
Pull-Down Current	IOL	53	-	53	mA	$VOL_{min} = 1.2v$, $VOL_{max} = 0.3V$		
Rise/Fall times	Tr, Tf	0.5	-	1.3	nS	35 pF Load, Measured @ 0.4V to 2.0V		
Clock High Time	Thi	5	-	-	nS	35 pF Load, Measured @ 2V		
Clock Low Time Tlo 5 nS 35 pF Load, Measured @ 0.4V								
VDD = VDD =3.3V +/- 5%, VDDC = 2.5V +/- 5%, TA = 0°C to +70°C								



Preliminary Product Information

BUF3 (PCI clocks)								
Characteristic	Characteristic Symbol Min Typ Max Units Conditions							
Pull-Up Current	IOH	-33	-	-33	mA	$VOH_{min} = 1.0V$, $VOH_{max} = 2.6$		
Pull-Down Current	IOL	30	-	38	mA	$VOL_{min} = 1.2v$, $VOL_{max} = 0.3V$		
Rise/Fall times	Tr, Tf	0.4	-	2.0	nS	20 pF Load, Measured @ 0.4V to 2.0V		
Clock High Time Thi 5 nS 20 pF Load, Measured @ 2V								
Clock Low Time Tlo 5 - nS 20 pF Load, Measured @ 0.4V								
VDD = VDD =3.3V +/- 5%, VDDC = 2.5V +/- 5%, TA = 0°C to +70°C								

BUF4 (IOAPIC and fixed clocks)								
Characteristic Symbol Min Typ Max Units Conditions								
Pull-Up Current	IOH	-29	-	-29	mA	$VOH_{min} = 1.0V, VOH_{max} = 2.6$		
Pull-Down Current	IOL	28	-	28	mA	$VOL_{min} = 1.2v$, $VOL_{max} = 0.3V$		
Rise/Fall times	Tr, Tf	0.4	-	1.6	nS	20 pF Load, Measured @ 0.4V to 2.0V		
Clock High Time	Thi	5	-	-	nS	20 pF Load, Measured @ 2V		
Clock Low Time Tlo 5 - nS 20 pF Load, Measured @ 0.4V								
VDD = VDD =3.3V +/- 5%, VDDC = 2.5V+/- 5%, TA = 0°C to +70°C								



Preliminary Product Information

CRYSTAL AND REFERENCE OSCILLATOR PARAMETERS								
Characteristic	Symbol	Min	Тур	Max	Units	Conditions		
Frequency	Fo	12.00	14.31818	16.00	MHz			
Tolerance	TC	-	-	+/-100	PPM	Calibration note 1		
	TS	-	ı	+/- 100	PPM	Stability (Ta -10 to +60C) note 1		
	TA	-	ı	5	PPM	Aging (first year @ 25C) note 1		
Mode	ОМ	-	-	-		Parallel Resonant		
Pin Capacitance	CP		5		pF	Capacitance of XIN and Xout pins		
DC Bias Voltage	V_{BIAS}	0.3Vdd	Vdd/2	0.7Vdd	V			
Startup time	Ts	-	-	30	μS			
Load Capacitance	CL	-	18	-	pF	note 1		
Effective Series resonant resistance	R1	-	-	40	Ohms			
Power Dissipation	DL	-	-	0.10	mW	note 1		
Shunt Capacitance	CO	-		7	pF			

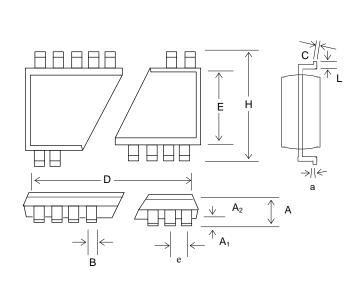
For maximum accuracy, the total circuit loading capacitance should be equal to CL. This loading capacitance is the effective capacitance across the crystal pins and includes the device pin capacitance (CP) in parallel with any circuit traces, the clock generator and any onboard discrete load capacitors. Typical trace capacitance, for traces less than a inch are 4 pF. with an internal pin capacitance of 5 pF the total parasitic capacitance would be 9 pF. It this instance a27 pF capacitor added to both legs (pins) of the crystal would bring its total load the recommended 18 pF CL pF each leg) .

Note 1: It is recommended but not mandatory chooses a crystal that meets these specifications.



Preliminary Product Information

PACKAGE DRAWING AND DIMENSIONS



48 PIN SSOP OUTLINE DIMENSIONS								
		INCHES		MILLIMETERS				
SYMBOL	MIN	NOM	MAX	MIN	NOM	MAX		
Α	-	-	0.110	0	0	2.79		
A ₁	0.008	0.012	0.016	0.20	0.30	0.41		
A2	0.085	0.090	0.095	2.16	2.29	2.41		
b	0.008	0.010	0.013	0.20	0.25	0.33		
С	0.006	0.008	0.010	0.15	0.20	0.25		
D	-	0.625	0.637	-	15.88	16.18		
Е	0.291	0.295	0.299	7.39	7.49	7.59		
е		0.025 BS0			0.64 BSC	;		
Н	0.395	0.408	0.420	10.03	10.36	10.67		
L	0.025	0.030	0.040	0.64	0.76	1.02		
а	0°	5°	80	0°	5°	80		

ORDERING INFORMATION						
Part Number	Part Number Package Type Production Flow					
IMISG654AYB	48 PIN SSOP	Commercial, 0°C to +70°C				

<u>Note</u>: The ordering part number is formed by a combination of device number, device revision, package style, and screening.

Note: Purchase of l^2C components of International Microcircuits, Inc. or one of its sublicensed Associated Companies conveys a license under the Philips l^2C Patent Rights to use these components in an l^2C system, provided that the system conforms to the l^2C Standard Specification as defined by Philips.